

# BAX52 - BAX53

## ULTRA FAST DIODE BRIDGE ASSEMBLIES

### SILICON PLANAR EPITAXIAL DIODES

**GENERAL DESCRIPTION** - These silicon PLANAR epitaxial diode bridges are designed for very high speed applications. They are hermetically sealed in either TO-5 or TO-18 packages. The excellent thermal conductivity of the packages permits operation up to 400 mW.

#### ABSOLUTE MAXIMUM RATINGS of each diode (Note 1)

##### Maximum Temperatures

$T_{STG}$ Storage Temperature	-55°C to +200°C
$T_A$ Operating Temperature	+175°C Maximum

##### Maximum Power Dissipation (Note 2)

P Total Dissipation at 25°C Ambient Temperature	0.4 Watt
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##### Maximum Voltage ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

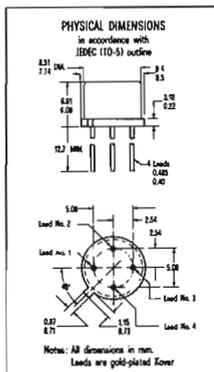
WIV Working Inverse Voltage	40 Volts
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##### Maximum Currents ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

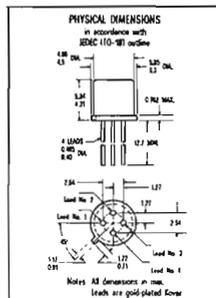
$I_F$ Forward Continuous DC Current	300 mA
$I_O$ Average Rectified Current	200 mA
$i_F$ (surge) Peak Forward Surge Current (1 sec. Pulse Width)	1 Amp.
$i_F$ (surge) Peak Forward Surge Current (1 $\mu\text{sec.}$ Pulse Width)	4 Amps.

#### ELECTRICAL CHARACTERISTICS of each diode (25°C free air temperature unless otherwise noted)

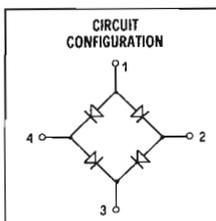
SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
$V_F$	Forward Voltage (Note 3)	0.98	1.15	1.5	V	$I_F = 500 \text{ mA}$
$V_F$	Forward Voltage (Note 3)	0.94	1.05	1.2	V	$I_F = 300 \text{ mA}$
$V_F$	Forward Voltage (Note 3)	0.89	0.98	1.1	V	$I_F = 200 \text{ mA}$
$V_F$	Forward Voltage (Note 3)	0.82	0.88	1	V	$I_F = 100 \text{ mA}$
$V_F$	Forward Voltage (Note 3)	0.75	0.8	0.9	V	$I_F = 50 \text{ mA}$
$V_F$	Forward Voltage	0.65	0.68	0.75	V	$I_F = 10 \text{ mA}$
$V_F$	Forward Voltage	0.63	0.65	0.71	V	$I_F = 5 \text{ mA}$
$V_F$	Forward Voltage	0.55	0.58	0.66	V	$I_F = 1 \text{ mA}$
$I_R$	Reverse Current	20	100	nA	$V_R = 40 \text{ V}$	
$I_R$ (125°C)	Reverse Current	15	100	$\mu\text{A}$	$V_R = 40 \text{ V}$	
BV	Breakdown Voltage	60		V	$I_R = 100 \mu\text{A}$	
$\tau_{rr}$	Reverse Recovery Time (Note 4)		25	nsec	$I_F = I_R = 10 \div 200 \text{ mA}$	
$C_O$	Capacitance (Note 5)		3	pF	$V_R = 0$ $f = 1 \text{ MHz}$	
$\Delta V_F / ^\circ\text{C}$	Forward Voltage Temperature Coefficient	-1.8		mV/°C		



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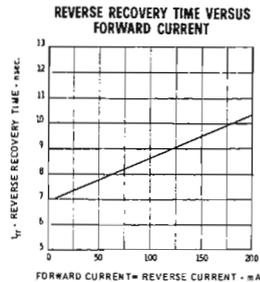
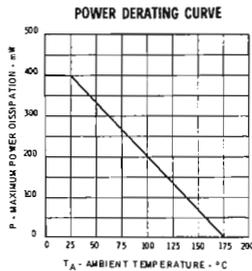
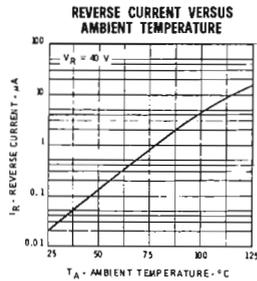
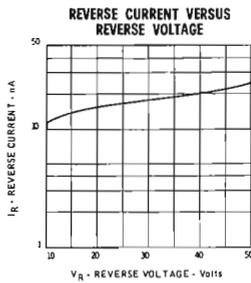
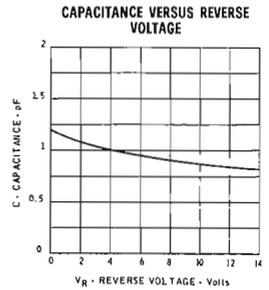
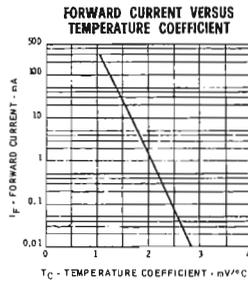
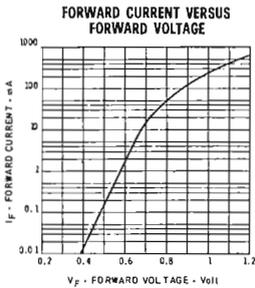


### BAX53



TYPICAL ELECTRICAL CHARACTERISTICS OF EACH DIODE

(25° C free air temperature unless otherwise noted)



NOTES:

- (1) Ratings apply to individual diodes. For multiple diode operation total power must not exceed power dissipation rating listed.
- (2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
- (3) Pulse Conditions: length = 300  $\mu$ sec; duty cycle = 1%.
- (4) Recovery to 10% of  $i_R$ .
- (5) Capacitance  $C_0$  cannot be monitored independently on each diode in a bridge configuration. In measuring this parameter on bridge configurations, the capacitance limit is 4/3 the limit listed in the electrical characteristics.